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The technical content of this austriamicrosystems datasheet is still valid.

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Datasheet

AS1360 1.5µA Low-Power, Positive Voltage Regulator

1 General Description

The AS1360 low-power, positive voltage regulator was designed to deliver up to 250mA while consuming only 1.5μ A of quiescent current. The device is available in fixed output voltages of 1.8, 2.1, 2.5, 3.0, 3.3, 4.0, 4.5 and 5.0V.

The device features integrated short-circuit and overcurrent protection.

The wide input voltage range, low-dropout voltage, and high-accuracy output voltage makes the device perfectly suited for 2- and 3- cell battery-powered and portable applications.

The low dropout voltage (650mV) prolongs battery life and allows high current in small applications when operated with minimum input-to-output voltage differentials.

The device features very stable output voltage (using only 1µF tantalum or aluminum-electrolytic capacitors), strict output voltage regulation tolerances ($\pm 0.5\%$), and excellent line-regulation.

The AS1360 is available in a 3-pin SOT23 package.

2 Key Features

- Low Quiescent Current: 1.5µA
- Input Voltage Range: Up to 20V
- Low Dropout Voltage
- 250mV @ 100mA
- 400mV @ 200mA
- Fixed Output Voltages: 1.8, 2.1, 2.5, 3.0, 3.3, 4.0, 4.5, 5.0V
- High Output Current: 250mA (VOUT = 5.0V)
- High-Accuracy Output Voltage: ±1.5%
- Exceptional Line Regulation: 0.1%/V
- Low Temperature Drift: ±100ppm/°C
- Integrated Short-Circuit and Overcurrent Protection
- 3-pin SOT23 Package

3 Applications

The device is ideal for mobile phones, PDAs, digital cameras, smart battery packs, battery-powered alarms, solar-powered instruments, intelligent instruments, CO2 and smoke detectors, CPU power supplies, and any battery-powered application.

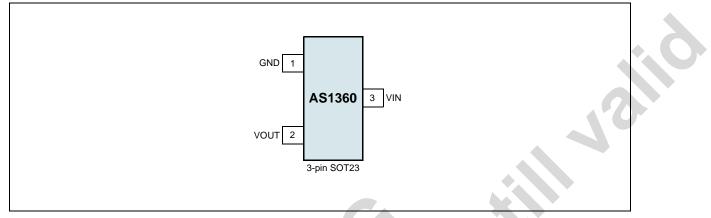
VIN VIN VIN VIN VIN VOUT VOUT Protection Protection Votage Reference AS1360

Figure 1. AS1360 - Block Diagram

4 Pinout and Packaging

Pin Assignments

Figure 2. Pin Assignments (Top View)



Pin Descriptions

Table 1. Pin Descriptions

1 Ground. This pin should be connected to the negative side of the output and the negative terminal of the input capacitor. No high-current flows out of this pin, only bias current (1.5) typ). 1 Note: Voltage drops between this pin and the negative side of the load should be minimized. 2 VOUT 2 VOUT Regulated Output Voltage. This pin should be connected to the positive side of the load a the positive terminal of the output capacitor. Current flowing out of this pin is equivalent D load current. Note: The positive side of the output capacitor should be mounted as close as is practitive side of the output capacitor should be mounted as close as is practitive side of the output capacitor should be mounted as close as is practitive side of the output capacitor should be mounted as close as is practitive side of the output capacitor should be mounted as close as is practitive side of the output capacitor should be mounted as close as is practitive side of the output capacitor should be mounted as close as is practitive side of the output capacitor should be mounted as close as is practitive side of the output capacitor should be mounted as close as is practitive side of the output capacitor should be mounted as close as is practitive side of the output capacitor should be mounted as close as is practitive side of the output capacitor should be mounted as close as is practine.
2 VOUT the positive terminal of the output capacitor. Current flowing out of this pin is equivalent D load current. Note: The positive side of the output capacitor should be mounted as close as is practi
3 VIN Unregulated Input Voltage. This pin should be connected to the positive terminal of the in capacitor. Note: The input capacitor should be mounted as close as is practical to this pin.

5 Absolute Maximum Ratings

Stresses beyond those listed in Table 2 may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in Section 6 Electrical Characteristics on page 4 is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 2	Abooluto	Movimum	Dotingo
Idule Z.	Absolute	Maximum	raunus

Electrostatic Discharge HBM +/- 1 kV Norm: MIL 883 E method 3015	Parameter	Min	Мах	Units	Comments
Continuous Output Current PD/ (VIN - VOUT) mA Peak Output Voltage - 0.3V VIN + 0.3V or +7V V Minimum of the two values Electrostatic Discharge - <td< td=""><td>Electrical Parameters</td><td>1</td><td>-<u>r</u></td><td></td><td></td></td<>	Electrical Parameters	1	- <u>r</u>		
Continuous Output Current (VIN - VOUT) ITIA Peak Output Voltage -0.3V VIN + 0.3V or +7V V Minimum of the two values Electrostatic Discharge -0.3V VIN + 0.3V or +7V V Minimum of the two values Electrostatic Discharge -0.3V VIN + 0.3V or +7V V Minimum of the two values Electrostatic Discharge +1/-1 KV Norm: MIL 883 E method 3015 Thermal Resistance OJA 230 °C/W Typical FR4, 4-layer application Temperature Ranges and Storage Conditions - - - Storage Temperature Range -40 +125 °C - - Package Body Temperature +260 °C The reflow peak soldering temperature (body temperature) specified is in compliance with IPC/ JEDEG J-STD-020 Molsture/ Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices': Humidity non-condensing 5 85 % Moisture Sensitive Level 1 Represents a max. floor life time of unlimited	Input Voltage		+30	V	
Output Voltage - 0.3V VIN + 0.3V or +7V V Minimum of the two values Electrostatic Discharge Electrostatic Discharge HBM +/- 1 KV Norm: MIL 883 E method 3015 Thermal Information Tarmal Resistance OJA 230 °C/W Typical FR4, 4-layer application Temperature Ranges and Storage Conditions Storage Temperature Range -40 +125 °C Package Body Temperature +260 °C The reflow peak soldering temperature (body temperature) specified is in compliance with I/PC/ JEDECU-STD-202 /Moisture/ Reflow Sensitivity Classification for Non-Hermetic Sold State Surface Mount Devices*. Humidity non-condensing 5 85 %	Continuous Output Current		PD/ (Vin - Vout)	mA	
Output Voltage -0.3V or +7V V Winnitum of the WO Values Electrostatic Discharge Electrostatic Discharge HBM +/-1 kV Norm: MIL 883 E method 3015 Thermal Information Typical FR4, 4-layer application Temperature Ranges and Storage Conditions Storage Temperature Range -40 +125 °C Storage Temperature Range -40 +125 °C The reflow peak soldering temperature (body temperature (body temperature) specified is in compliance with <i>IPC/ JEDEC J-STD-020 *Moisture/ Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices</i> *. Humidity non-condensing 5 85 %	Peak Output Current		500	mA	
Electrostatic Discharge HBM +/-1 kV Norm: MIL 883 E method 3015 Thermal Information Typical FR4, 4-layer application Temperature Ranges and Storage Conditions Storage Temperature Range -40 +125 °C Storage Temperature Range -40 +125 °C The reflow peak soldering temperature (body temperature) specified is in compliance with <i>IPC/JEDEC J-STD-202</i> Wolsture/ Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices". Humidity non-condensing 5 85 % Moisture Sensitive Level 1 Represents a max. floor life time of unlimited	Output Voltage	- 0.3V		V	Minimum of the two values
Thermal Information 230 °C/W Typical FR4, 4-layer application Temperature Ranges and Storage Conditions Storage Temperature Range -40 +125 °C Storage Temperature Range -40 +125 °C The reflow peak soldering temperature (body temperature) specified is in compliance with IPC/JEDEG J-STD-020 'Moisture/ Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices'. Humidity non-condensing 5 85 % Moisture Sensitive Level 1 Represents a max. floor life time of unlimited	Electrostatic Discharge		+		
Thermal Resistance OJA 230 °C/W Typical FR4, 4-layer application Storage Temperature Range -40 +125 °C Package Body Temperature +260 °C The reflow peak soldering temperature (body temperature) specified is in compliance with IPC/JEDEC J-STD-020 "Moisture/Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices". Humidity non-condensing 5 85 % Moisture Sensitive Level 1 Represents a max. floor life time of unlimited	Electrostatic Discharge HBM		+/- 1	kV	Norm: MIL 883 E method 3015
Temperature Ranges and Storage Conditions Storage Temperature Range -40 +125 °C Package Body Temperature +260 °C The reflow peak soldering temperature (body temperature) specified is in compliance with <i>IPC/ JEDEC J-STD-020 "Moisture/ Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices".</i> Humidity non-condensing 5 85 % Moisture Sensitive Level 1 Represents a max. floor life time of unlimited	Thermal Information				
Storage Temperature Range -40 +125 °C Package Body Temperature +260 °C The reflow peak soldering temperature (body temperature) specified is in compliance with IPC/JEDEC J-STD-020 "Moisture' Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices". Humidity non-condensing 5 85 % Moisture Sensitive Level 1 Represents a max. floor life time of unlimited	Thermal Resistance OJA		230	°C/W	Typical FR4, 4-layer application
Package Body Temperature +260 °C The reflow peak soldering temperature (body temperature) specified is in compliance with IPC/JEDEC J-STD-020 "Moisture/ Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices". Humidity non-condensing 5 85 % Moisture Sensitive Level 1 Represents a max. floor life time of unlimited	Femperature Ranges and Storage Con	ditions			
Package Body Temperature +260 °C The reflow peak soldering temperature (body temperature) specified is in compliance with <i>IPC/JEDEC J-STD-020</i> "Moisture/ Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices". Humidity non-condensing 5 85 % Moisture Sensitive Level 1 Represents a max. floor life time of unlimited	Storage Temperature Range	-40	+125	°C	
Moisture Sensitive Level 1 Represents a max. floor life time of unlimited	Package Body Temperature		+260	°C	The reflow peak soldering temperature (body temperature) specified is in compliance with IPC/ JEDEC J-STD-020 "Moisture/ Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices".
	Humidity non-condensing	5	85	%	
	• •	5	85	%	

6 Electrical Characteristics

Typical values are at TAMB = $+25^{\circ}$ C, VDD = 3.3V (unless otherwise specified). All limits are guaranteed. The parameters with min and max values are guaranteed with production tests or SQC (Statistical Quality Control) methods.

Table 3. Electrical Charact

Symbol	Parameter	Condition	Min	Тур	Max	Unit	
Тамв	Operating Temperature Range		-40		+85	°C	
Vin	Input Voltage				20	V	
Vout	Output Voltage	IOUT = 40mA ¹ , IOUT = 15mA if VOUT = 1.8V	Voutnom - 1.5%	Voutnom ± 0.5%	Voutnom + 1.5%	V	
		Vout = 5.0V (Vin = Voutnom + 1.0V)	250				
	MAX) Maximum Output Current	Vout = 4.0V	200				
		Vout = 3.3V	150				
IOUT(MAX)		Vout = 3.0V	150			mA	
		Vout = 2.5V	125				
		Vout = 2.1V	115				
		Vout = 1.8V	110				
ΔVout/Vout	Load Regulation ²	Vout = 5.0V, $1\text{mA} \le 100\text{mA}$	-1.60	±0.8	+1.60		
		VOUT = 4.0V, $1\text{mA} \le \text{IOUT} \le 100\text{mA}$	-2.25	±1.1	+2.25	%	
		Vout = 3.3V, 1mA ≤ Iout ≤ 80mA	-2.72	±1.3	+2.72		
		Vout = 3.0V, 1mA ≤ Iout ≤ 80mA	-3.00	±1.5	+3.00		
		VOUT = 2.5V, 1mA ≤ IOUT ≤ 60mA	-3.60	±1.8	+3.60		
		Vout = 2.1V, 1mA ≤ Iout ≤ 40mA	-2.60	±1.6	+2.60		
		VOUT = 1.8V, 1mA ≤ IOUT ≤ 30mA	-1.60	±0.8	+1.60		
$\Delta VOUT x 100/$ $\Delta VIN x VOUT$	Line Regulation	IOUT = 40mA, (VOUTNOM +1.0) ≤ VIN ≤ 10.0V		0.1	0.25	%/V	
	40	IOUT = 200mA, VOUTNOM = 5.0V		400	630		
		IOUT = 200mA, VOUTNOM = 4.0V		400	700		
Vin - Vout	Dropout Voltage	IOUT = 160mA, VOUTNOM = 3.3V		400	700		
		IOUT = 160mA, VOUTNOM = 3.0V		400	700	mV	
		IOUT = 120mA, VOUTNOM = 2.5V		400	700		
		IOUT = 60mA, VOUTNOM = 2.1V		200	500		
		lout = 20mA, Voutnom = 1.8V		180	300		
IQ	Input Quiescent Current	VIN = VOUTNOM +1.0V		1.5	3.0	μA	
TCVout	Temperature Coefficient of VOUT ³	lout = 40mA, -40°С ≤ Тамв ≤ +85°С		±100		ppm/ºC	
tR	Output Rise Time	10% Voutnom to 90% Voutnom, Vin = 0V to Voutnom + 1V, RLOAD = 25Ω resistive		150		μs	

1. VOUTNOM is the nominal device output voltage.

2. Measured at a constant junction temperature using low duty cycle pulse testing.

3. TCVOUT = (VOH - VOL) x 10⁶/(VOUTNOM x Temperature). Where:

VOH is the highest voltage measured over the device temperature range. VOL is the lowest voltage over the device temperature range.

7 Typical Operating Characteristics

VOUT = 3.3V, $ILOAD = 100\mu A$, VIN = 4.3V, $CIN 1\mu F$ (tantalum), $COUT = 1\mu F$ (tantalum), $TAMB = +25^{\circ}C$ (unless otherwise specified).

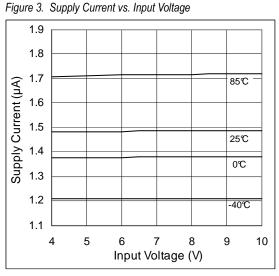
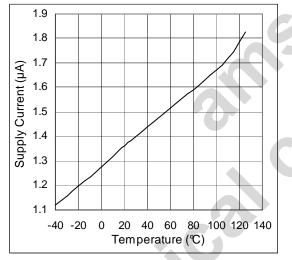
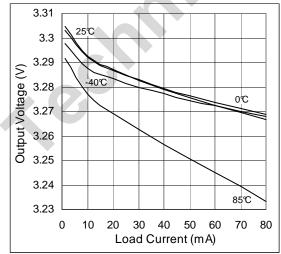


Figure 5. Supply Current vs. Temperature







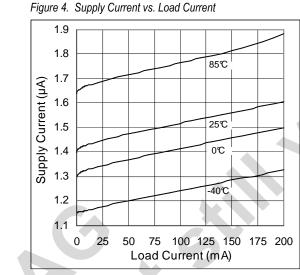


Figure 6. Output Voltage vs. Input Voltage

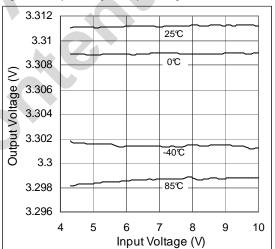


Figure 8. Dropout Voltage vs. Load Current

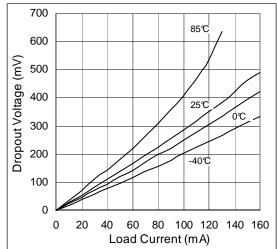


Figure 9. Load Regulation vs. Temperature

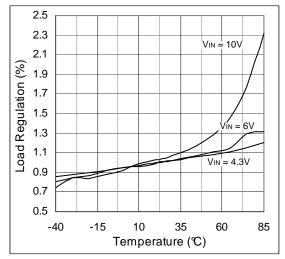
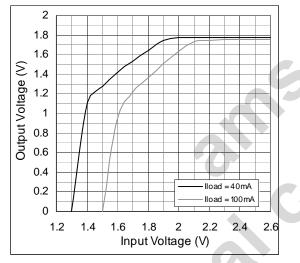


Figure 11. Output Voltage vs. Input Voltage; Dropout



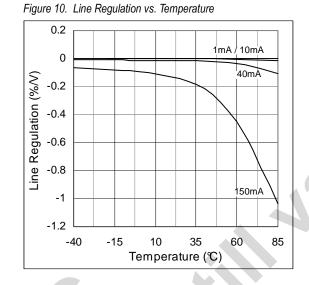


Figure 12. Startup Rise Time

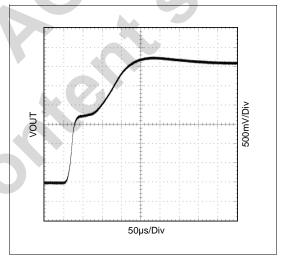
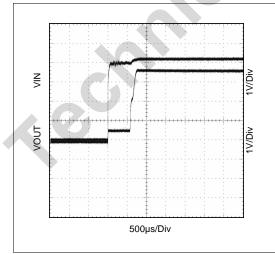


Figure 13. Startup Delay



Note: All graphs where measured without additional heat sinks, with the SOT23 package mounted on a 4-layer PCB. Adding additional heat sinks will improve performance in high temperature enviroment.

8 Detailed Description

The AS1360 is a low-power, positive voltage regulator designed in such a way that the supply current is independent from the load current. The device regulates the output by comparing the output voltage to an internally generated reference voltage.

The device is available in fixed output voltages of 1.8, 2.5, 3.0, 3.3, and 5.0V. Fixed output voltages are generated using the internal resistor divider network (see Figure 1 on page 1).

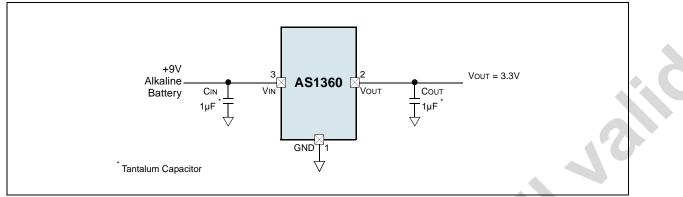
Short Circuit/Overcurrent Protection

The AS1360 monitors current flow through the p-channel MOSFET. In short-circuit or overcurrent conditions, the integrated short-circuit protection circuitry will limit output current.

Note: Thermal Dissipation according to Absolute Maximum Ratings on page 3 must be considered.

9 Application Information

Figure 14. AS1360 - Typical Application Diagram



Power Dissipation

Power dissipation (PD) of the AS1360 is the sum of the power dissipated by the p-channel MOSFET and the quiescent current required to bias the internal voltage reference and the internal power amplifier, and is calculated as:

Internal power dissipation as a result of the bias current for the internal voltage reference and the error amplifier is calculated as:

$$PD$$
 (Bias) = VINIGND (EQ 2)

Total AS1360 power dissipation is calculated as:

The internal quiescent bias current (2µA, typ) is such that the PD(Bias) term of (EQ 3) can be disregarded and the maximum power dissipation can be estimated using VIN(MAX) and VOUT(MIN) to obtain a maximum voltage differential between VIN and VOUT, and multiplying the maximum voltage differential by the maximum output current:

$$PD = (VIN(MAX)VOUT(MIN))IOUT(MAX)$$
(EQ 4)

Where:

VIN = 3.3 to 4.1V VOUT = 3.0V ±2% IOUT = 1 to 100mA TAMB(MAX) = 55°C PMAX = (4.1V - (3.0V x 0.98)) x 100mA = 116.0mW

Junction Temperature

The AS1360 junction temperature (TJ) can be determined by first calculating the thermal resistance from junction temperature-to-ambient temperature.

Note: Thermal resistance is estimated to be the junction temperature-to-air temperature RΦJA, and is approximately 230°C/W or 335°C/W (when mounted on 1 square inch of copper). RΦJA will vary depending on PCB layout, air-flow and application specific conditions.

The AS1360 junction temperature is determined by calculating the rise in TJ above TAMB, and then adding the increase of TAMB:

$$T_J = P_{D(MAX)} \times R_{\Phi JA} + T_{AMB}$$
 (EQ 5)

From (EQ 5), the value of TJ can be calculated as:

TJ = 116.0mW x 230°C/W + 55°C

Therefore:

TJ = 81.68°C

External Component Selection

Input Capacitor

In applications where input impedance is approximately 10Ω, a 1µF capacitor is sufficient for CIN (see Figure 14 on page 8).

In cases where the AS1360 is operated from a battery, or when there is significant distance between the input source to the AS1360, larger values for CIN may be required for output stability.

Note: For values of COUT > 1µF, the value of CIN should be increased to prevent high source-impedance oscillations.

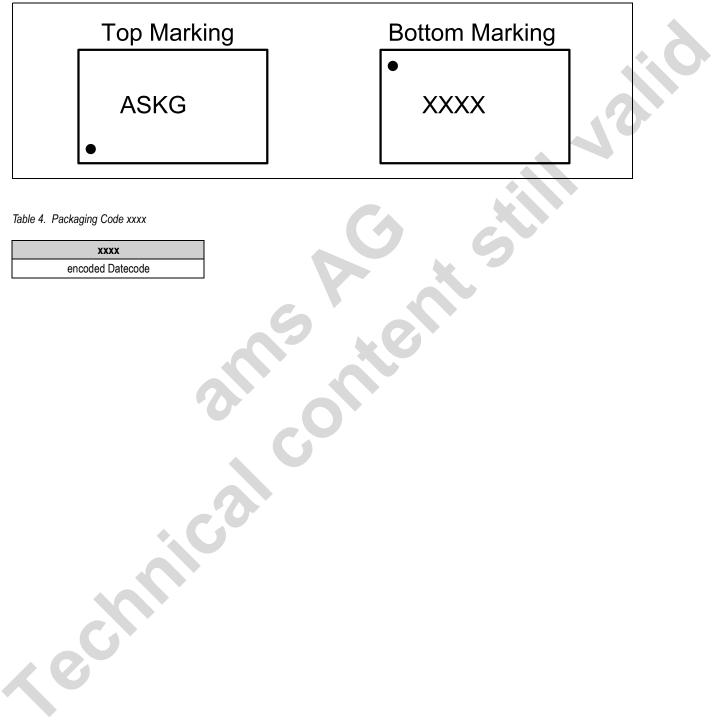
Output Capacitor

In most applications for the AS1360, a 1 μ F capacitor (ESR > 0.1 Ω /< 5 Ω , fRES > 1MHz) is sufficient for COUT (see Figure 14 on page 8). For improved power supply noise rejection and device transient response, larger values can be used for COUT.

Note: For values of COUT > 1μ F, the input impedance must not be so large that it causes high-input impedance oscillations.

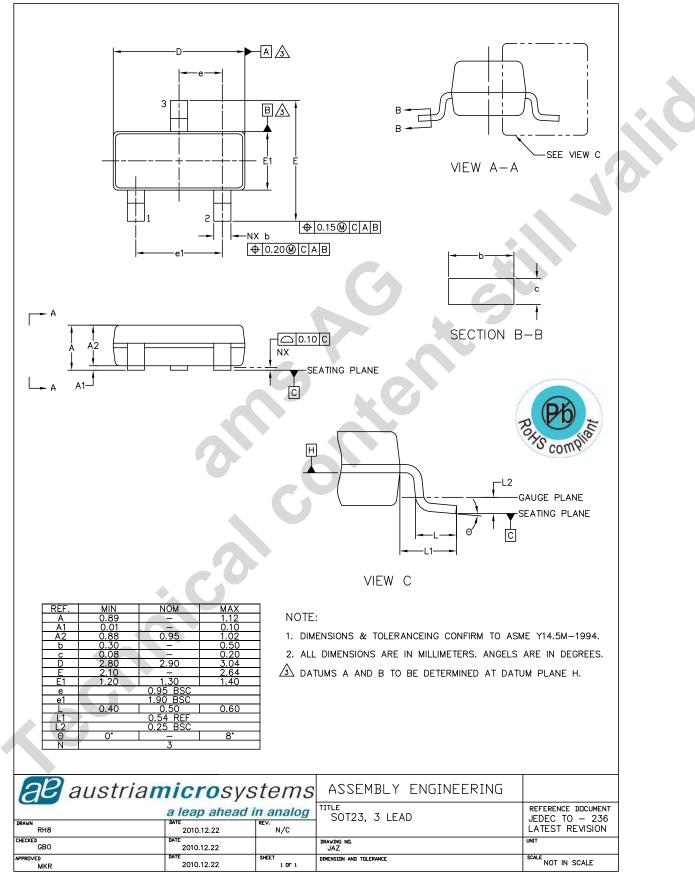
10 Package Drawings and Markings

Figure 15. 3-pin SOT23 Marking



Datasheet - Package Drawings and Markings

Figure 16. 3-pin SOT23 Package



11 Ordering Information

The device is available as the standard products shown in Table 5.

Table 5. Ordering Information

Ordering Code	Marking	Description	Delivery Form	Package
AS1360-18-T	ASKD	HV low-quiescent current LDO, 1.8V	Tape and Reel	3-pin SOT23
AS1360-21-T	ASRO	HV low-quiescent current LDO, 2.1V	Tape and Reel	3-pin SOT23
AS1360-25-T	ASKE	HV low-quiescent current LDO, 2.5V	Tape and Reel	3-pin SOT23
AS1360-30-T	ASKF	HV low-quiescent current LDO, 3.0V	Tape and Reel	3-pin SOT23
AS1360-33-T	ASKG	HV low-quiescent current LDO, 3.3V	Tape and Reel	3-pin SOT23
AS1360-40-T	ASQV	HV low-quiescent current LDO, 4.0V	Tape and Reel	3-pin SOT23
AS1360-45-T	ASTQ	HV low-quiescent current LDO, 4.5V	Tape and Reel	3-pin SOT23
AS1360-50-T	ASKH	HV low-quiescent current LDO, 5.0V	Tape and Reel	3-pin SOT23

Note: All products are RoHS compliant.

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